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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	8KB (2.75K x 24)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f08kl302t-i-ss

Analog Features:

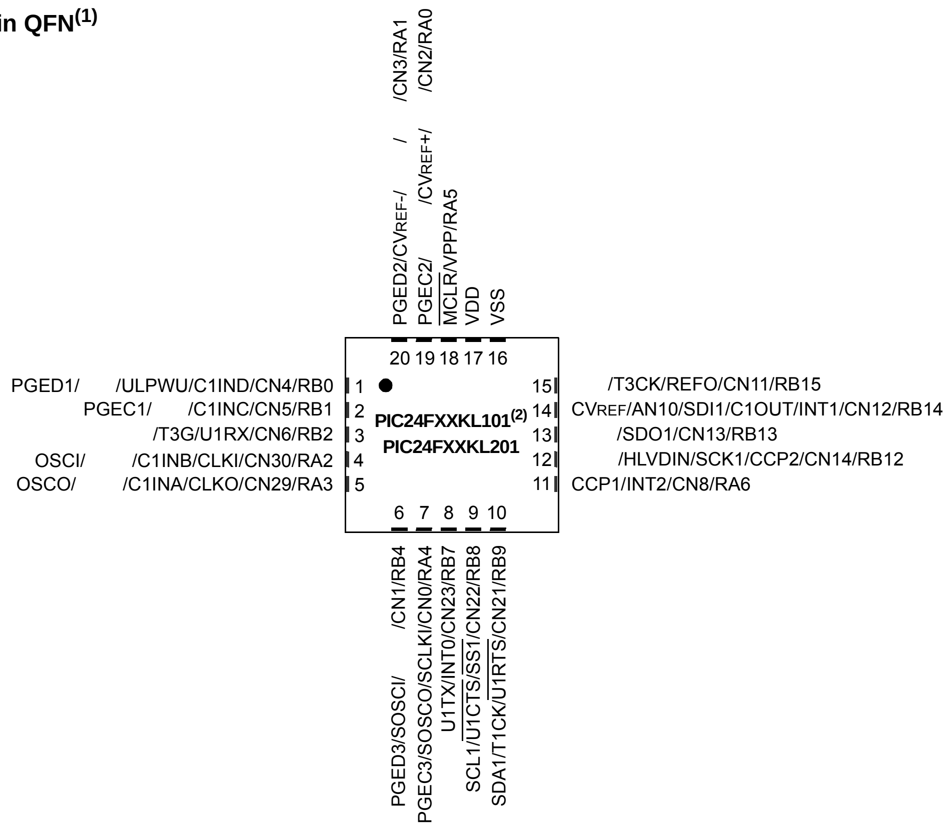
- 10-Bit, up to 12-Channel Analog-to-Digital (A/D) Converter:
  - 500 ksps conversion rate
  - Conversion available during Sleep and Idle
- Dual Rail-to-Rail Analog Comparators with Programmable Input/Output Configuration
- On-Chip Voltage Reference

Special Microcontroller Features:

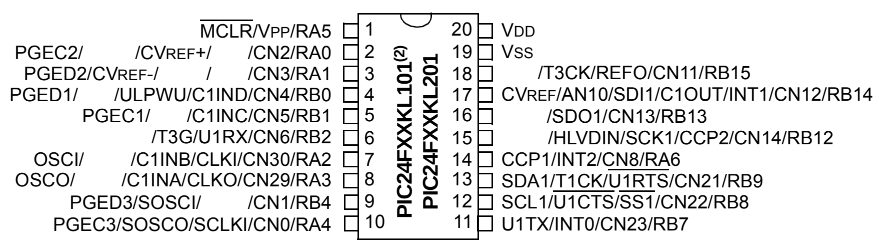
- Operating Voltage Range of 1.8V to 3.6V
- 10,000 Erase/Write Cycle Endurance Flash Program Memory, Typical
- 100,000 Erase/Write Cycle Endurance Data EEPROM, Typical
- Flash and Data EEPROM Data Retention: 40 Years Minimum
- Self-Programmable under Software Control
- Programmable Reference Clock Output
- Fail-Safe Clock Monitor (FSCM) Operation:
  - Detects clock failure and switches to on-chip, Low-Power RC (LPRC) oscillator
- Power-on Reset (POR), Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- Flexible Watchdog Timer (WDT):
  - Uses its own Low-Power RC oscillator
  - Windowed operating modes
  - Programmable period of 2 ms to 131s
- In-Circuit Serial Programming™ (ICSP™) and In-Circuit Emulation (ICE) via 2 Pins
- Programmable High/Low-Voltage Detect (HLVD)
- Programmable Brown-out Reset (BOR):
  - Configurable for software controlled operation and shutdown in Sleep mode
  - Selectable trip points (1.8V, 2.7V and 3.0V)
  - Low-power 2.0V POR re-arm

Pin Diagrams: PIC24FXXKL10X/20X

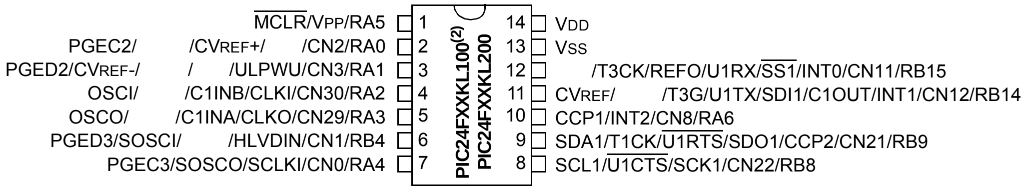
20-Pin QFN(1)



20-Pin PDIP/SSOP/SOIC(1)



14-Pin PDIP/TSSOP(1)



Note 1: Analog features (indicated in) are not available on PIC24FXXKL100/101 devices.

2: Alternate location for I^{2}C™ functionality of MSSP1, as determined by the I2C1SEL Configuration bit.

2.4 ICSP Pins

The PGC and PGD pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of ohms, not to exceed 100Ω.

Pull-up resistors, series diodes and capacitors on the PGC and PGD pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits, and pin Input Voltage High (V_{IH}) and Input Voltage Low (V_{IL}) requirements.

For device emulation, ensure that the “Communication Channel Select” (i.e., PGCx/PGDx) pins, programmed into the device, matches the physical connections for the ICSP to the Microchip debugger/emulator tool.

For more information on available Microchip development tools connection requirements, refer to **Section 24.0 “Development Support”**.

2.5 External Oscillator Pins

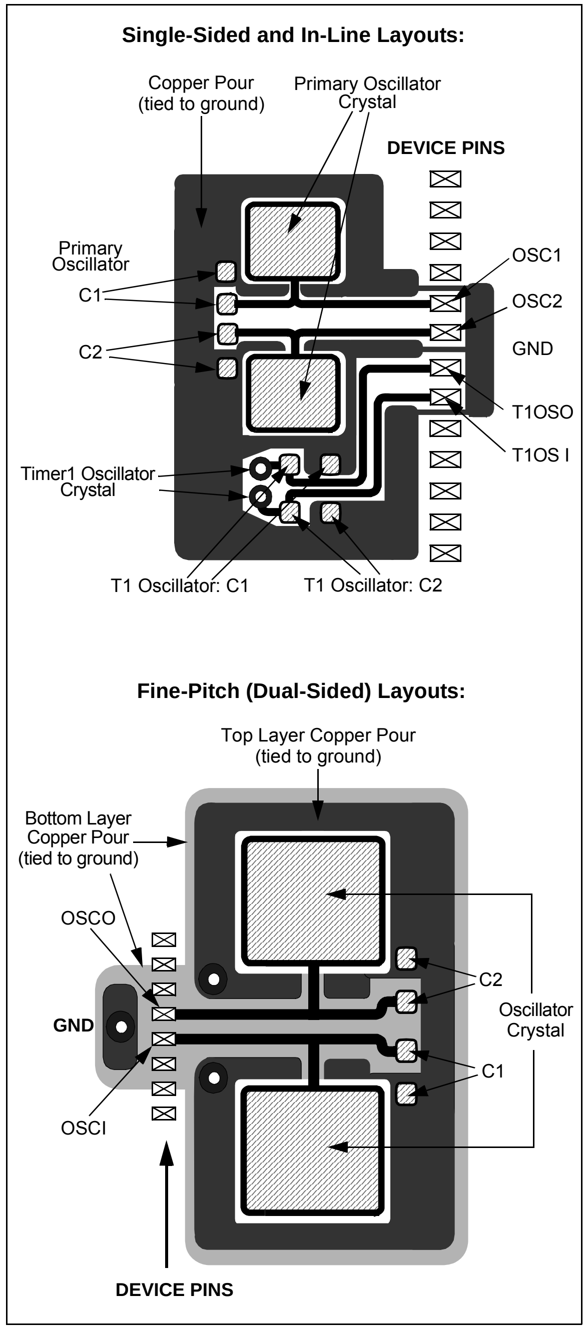
Many microcontrollers have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 9.0 “Oscillator Configuration”** for details).

The oscillator circuit should be placed on the same side of the board as the device. Place the oscillator circuit close to the respective oscillator pins with no more than 0.5 inch (12 mm) between the circuit components and the pins. The load capacitors should be placed next to the oscillator itself, on the same side of the board.

Use a grounded copper pour around the oscillator circuit to isolate it from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed.

Layout suggestions are shown in Figure 2-3. In-line packages may be handled with a single-sided layout that completely encompasses the oscillator pins. With fine-pitch packages, it is not always possible to completely surround the pins and components. A suitable solution is to tie the broken guard sections to a mirrored ground layer. In all cases, the guard trace(s) must be returned to ground.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



In planning the application’s routing and I/O assignments, ensure that adjacent port pins and other signals, in close proximity to the oscillator, are benign (i.e., free of high frequencies, short rise and fall times, and other similar noise).

TABLE 4-4: ICN REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CNPD1	0056	CN15PDE(1)	CN14PDE(1)	CN13PDE(1)	CN12PDE	CN11PDE	—	CN9PDE(2)	CN8PDE	CN7PDE(2)	CN6PDE(1)	CN5PDE(1)	CN4PDE(1)	CN3PDE	CN2PDE	CN1PDE	CN0PDE	0000
CNPD2	0058	—	CN30PDE	CN29PDE	—	CN27PDE(2)	—	—	CN24PDE(2)	CN23PDE(1)	CN22PDE	CN21PDE	—	—	—	—	CN16PDE(2)	0000
CNEN1	0062	CN15IE(1)	CN14IE(1)	CN13IE(1)	CN12IE	CN11IE	—	CN9IE(1)	CN8IE	CN7IE(1)	CN6IE(2)	CN5PIE(2)	CN4IE(2)	CN3IE	CNIE	CN1IE	CN0IE	0000
CNEN2	0064	—	CN30IE	CN29IE	—	CN27IE(2)	—	—	CN24IE(2)	CN23IE(1)	CN22IE	CN21IE	—	—	—	—	CN16IE(2)	0000
CNPU1	006E	CN15PUE(1)	CN14PUE(1)	CN13PUE(1)	CN12PUE	CN11PUE	—	CN9PUE(1)	CN8PUE	CN7PUE(1)	CN6PUE(2)	CN5PUE(2)	CN4PUE(2)	CN3PUE	CN2PUE	CN1PUE	CN0PUE	0000
CNPU2	0070	—	CN30PUE	CN29PUE	—	CN27PUE(2)	—	—	CN24PUE(2)	CN23PUE(1)	CN22PUE	CN21PUE	—	—	—	—	CN16PUE(2)	0000

Legend: — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: These bits are unimplemented in 14-pin devices; read as ‘0’.

2: These bits are unimplemented in 14-pin and 20-pin devices; read as ‘0’.

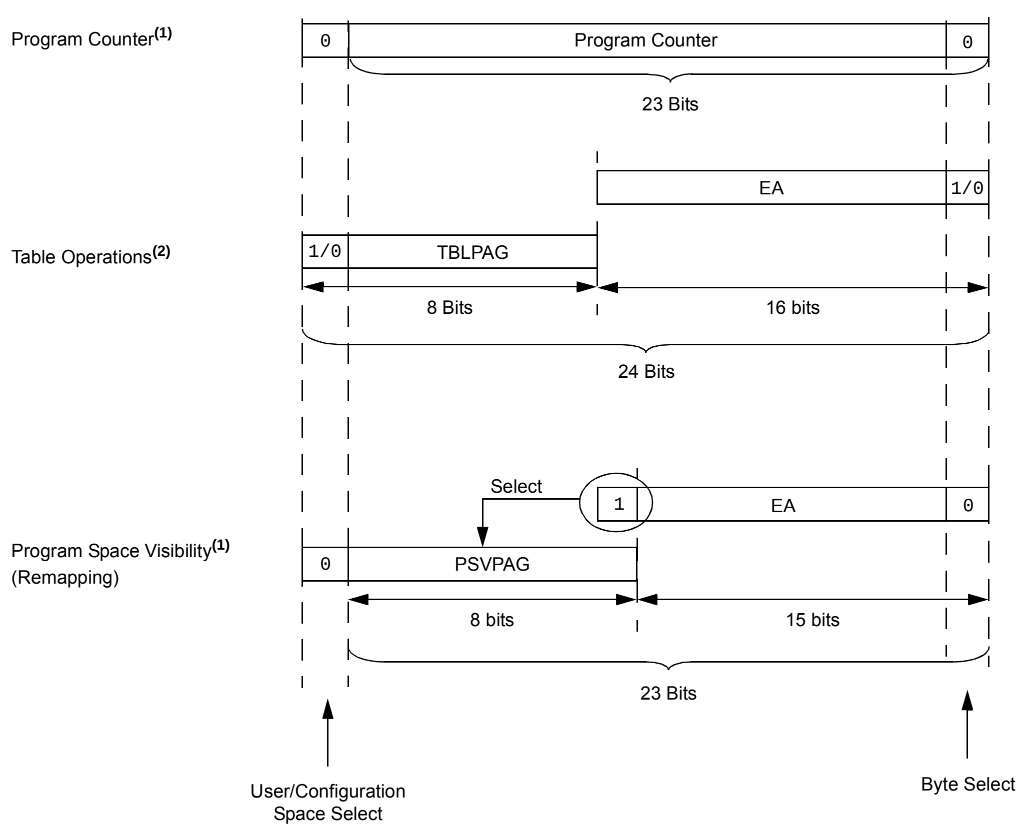
TABLE 4-20: PROGRAM SPACE ADDRESS CONSTRUCTION

Access Type	Access Space	Program Space Address				
		<23>	<22:16>	<15>	<14:1>	<0>
Instruction Access (Code Execution)	User	0	PC<22:1>			0
		0xx xxxx xxxx xxxx xxxx xxx0				
TBLRD/TBLWT (Byte/Word Read/Write)	User	TBLPAG<7:0>		Data EA<15:0>		
		0xxx xxxx		xxxx xxxx xxxx xxxx		
	Configuration	TBLPAG<7:0>		Data EA<15:0>		
		1xxx xxxx		xxxx xxxx xxxx xxxx		
Program Space Visibility (Block Remap/Read)	User	0	PSVPAG<7:0>[2]		Data EA<14:0>[1]	
		0	xxxx xxxx		xxx xxxx xxxx xxxx	

Note 1: Data EA<15> is always '1' in this case, but is not used in calculating the program space address. Bit 15 of the address is PSVPAG<0>.

2: PSVPAG can have only two values ('00' to access program memory and FF to access data EEPROM) on PIC24F16KL402 family devices.

FIGURE 4-5: DATA ACCESS FROM PROGRAM SPACE ADDRESS GENERATION



Note 1: The LSb of program space addresses is always fixed as '0' in order to maintain word alignment of data in the program and data spaces.

2: Table operations are not required to be word-aligned. Table read operations are permitted in the configuration memory space.

7.0 RESETS

> **Note:** This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on Resets, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Reset with Programmable Brown-out Reset"** (DS39728).

The Reset module combines all Reset sources and controls the device Master Reset Signal, SYSRST. The following is a list of device Reset sources:

- POR: Power-on Reset
- MCLR: Pin Reset
- SWR: RESET Instruction
- WDTR: Watchdog Timer Reset
- BOR: Brown-out Reset
- TRAPR: Trap Conflict Reset
- IOPUWR: Illegal Opcode Reset
- UWR: Uninitialized W Register Reset

A simplified block diagram of the Reset module is shown in Figure 7-1.

Any active source of Reset will make the SYSRST signal active. Many registers associated with the CPU and peripherals are forced to a known Reset state. Most registers are unaffected by a Reset; their status is unknown on a Power-on Reset (POR) and unchanged by all other Resets.

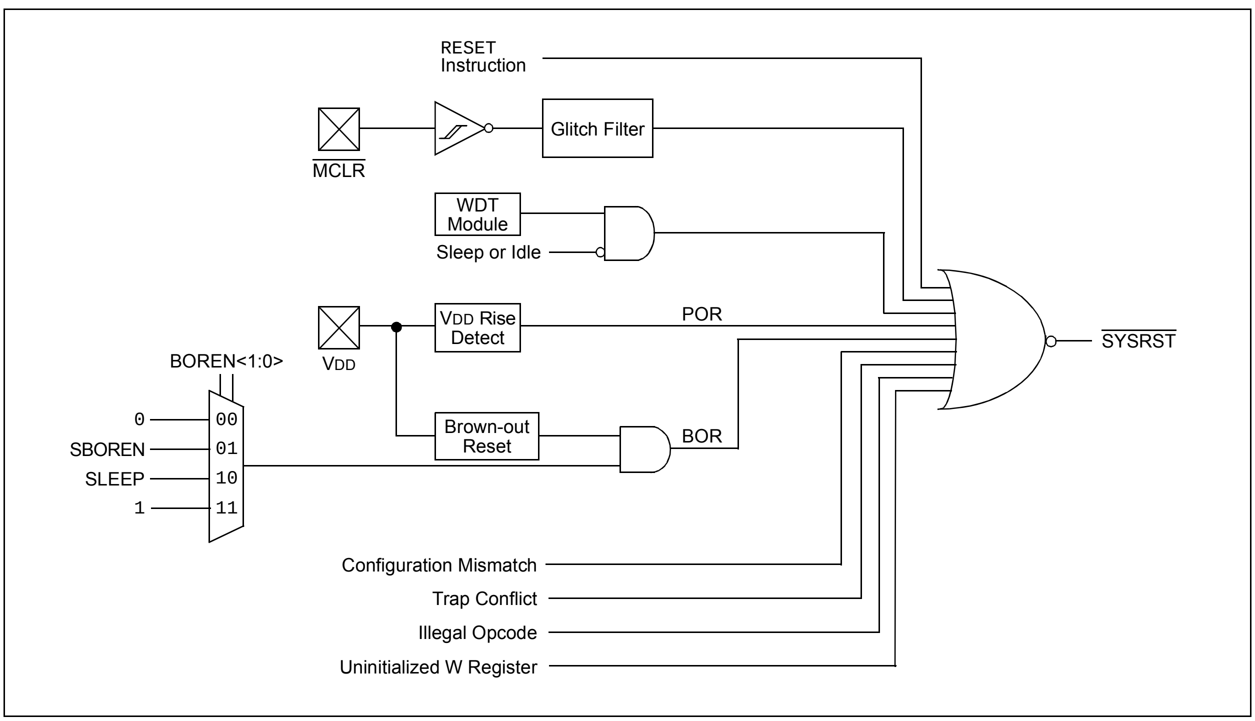
> **Note:** Refer to the specific peripheral or CPU section of this manual for register Reset states.

All types of device Reset will set a corresponding status bit in the RCON register to indicate the type of Reset (see Register 7-1). A POR will clear all bits except for the BOR and POR bits (RCON<1:0>) which are set. The user may set or clear any bit at any time during code execution. The RCON bits only serve as status bits. Setting a particular Reset status bit in software will not cause a device Reset to occur.

The RCON register also has other bits associated with the Watchdog Timer (WDT) and device power-saving states. The function of these bits is discussed in other sections of this manual.

> **Note:** The status bits in the RCON register should be cleared after they are read so that the next RCON register value, after a device Reset, will be meaningful.

FIGURE 7-1: RESET SYSTEM BLOCK DIAGRAM



8.0 INTERRUPT CONTROLLER

> **Note:** This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on the Interrupt Controller, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Interrupts"** (DS39707).

The PIC24F interrupt controller reduces the numerous peripheral interrupt request signals to a single interrupt request signal to the CPU. It has the following features:

- Up to eight processor exceptions and software traps
- Seven user-selectable priority levels
- Interrupt Vector Table (IVT) with up to 118 vectors
- Unique vector for each interrupt or exception source
- Fixed priority within a specified user priority level
- Alternate Interrupt Vector Table (AIVT) for debug support
- Fixed interrupt entry and return latencies

8.1 Interrupt Vector Table (IVT)

The IVT is shown in Figure 8-1. The IVT resides in the program memory, starting at location, 000004h. The IVT contains 126 vectors, consisting of eight non-maskable trap vectors, plus up to 118 sources of interrupt. In general, each interrupt source has its own vector. Each interrupt vector contains a 24-bit wide address. The value programmed into each interrupt vector location is the starting address of the associated Interrupt Service Routine (ISR).

Interrupt vectors are prioritized in terms of their natural priority; this is linked to their position in the vector table. All other things being equal, lower addresses have a higher natural priority. For example, the interrupt associated with vector 0 will take priority over interrupts at any other vector address.

PIC24F16KL402 family devices implement 32 non-maskable traps and unique interrupts; these are summarized in Table 8-1 and Table 8-2.

8.1.1 ALTERNATE INTERRUPT VECTOR TABLE (AIVT)

The Alternate Interrupt Vector Table (AIVT) is located after the IVT, as shown in Figure 8-1. Access to the AIVT is provided by the ALTIVT control bit (INTCON2<15>). If the ALTIVT bit is set, all interrupt and exception processes will use the alternate vectors instead of the default vectors. The alternate vectors are organized in the same manner as the default vectors.

The AIVT supports emulation and debugging efforts by providing a means to switch between an application and a support environment without requiring the interrupt vectors to be reprogrammed. This feature also enables switching between applications for evaluation of different software algorithms at run time. If the AIVT is not needed, the AIVT should be programmed with the same addresses used in the IVT.

8.2 Reset Sequence

A device Reset is not a true exception, because the interrupt controller is not involved in the Reset process. The PIC24F devices clear their registers in response to a Reset, which forces the Program Counter (PC) to zero. The microcontroller then begins program execution at location, 000000h. The user programs a `GOTO` instruction at the Reset address, which redirects the program execution to the appropriate start-up routine.

> **Note:** Any unimplemented or unused vector locations in the IVT and AIVT should be programmed with the address of a default interrupt handler routine that contains a `RESET` instruction.

REGISTER 8-15: IEC4: INTERRUPT ENABLE CONTROL REGISTER 4

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	HLVDIE
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	U-0
—	—	—	—	—	U2ERIE(1)	U1ERIE	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as ‘0’

bit 8 **HLVDIE:** High/Low-Voltage Detect Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 7-3 **Unimplemented:** Read as ‘0’

bit 2 **U2ERIE:** UART2 Error Interrupt Enable bit(1)
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 1 **U1ERIE:** UART1 Error Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 0 **Unimplemented:** Read as ‘0’

Note 1: This bit is unimplemented on PIC24FXXKL10X and PIC24FXXKL20X devices.

REGISTER 8-16: IEC5: INTERRUPT ENABLE CONTROL REGISTER 5

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
—	—	—	—	—	—	—	ULPWUIE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-1 **Unimplemented:** Read as ‘0’

bit 0 **ULPWUIE:** Ultra Low-Power Wake-up Interrupt Enable Bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

10.0 POWER-SAVING FEATURES

> **Note:** This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on Power-Saving Features, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Power-Saving Features with Deep Sleep"** (DS39727).

The PIC24F16KL402 family of devices provides the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. All PIC24F devices manage power consumption using several strategies:

- Clock frequency
- Instruction-based Idle and Sleep modes
- Hardware-based periodic wake-up from Sleep
- Software Controlled Doze mode
- Selective peripheral control in software

Combinations of these methods can be used to selectively tailor an application's power consumption, while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

PIC24F devices allow for a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSCx bits. The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.2 Instruction-Based Power-Saving Modes

PIC24F devices have two special power-saving modes that are entered through the execution of a special `PWRSAV` instruction. Sleep mode stops clock operation and halts all code execution; Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation.

The assembly syntax of the `PWRSAV` instruction is shown in Example 10-1.

> **Note:** `SLEEP_MODE` and `IDLE_MODE` are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

EXAMPLE 10-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV    #SLEEP_MODE    ; Put the device into SLEEP mode
PWRSAV    #IDLE_MODE     ; Put the device into IDLE mode
```


11.3 Input Change Notification

The Input Change Notification (ICN) function of the I/O ports allows the PIC24F16KL402 family of devices to generate interrupt requests to the processor in response to a Change-of-State (COS) on selected input pins. This feature is capable of detecting input Change-of-States, even in Sleep mode, when the clocks are disabled. Depending on the device pin count, there are up to 23 external signals that may be selected (enabled) for generating an interrupt request on a Change-of-State.

There are six control registers associated with the Change Notification (CN) module. The CNEN1 and CNEN2 registers contain the interrupt enable control bits for each of the CN input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

Each CN pin also has a weak pull-up/pull-down connected to it. The pull-ups act as a current source that is connected to the pin. The pull-downs act as a current sink to eliminate the need for external resistors when push button or keypad devices are connected.

On any pin, only the pull-up resistor or the pull-down resistor should be enabled, but not both of them. If the push button or the keypad is connected to V_{DD}, enable the pull-down, or if they are connected to V_{SS}, enable the pull-up resistors. The pull-ups are enabled separately using the CNPU1 and CNPU2 registers, which contain the control bits for each of the CN pins.

Setting any of the control bits enables the weak pull-ups for the corresponding pins. The pull-downs are enabled separately, using the CNPD1 and CNPD2 registers, which contain the control bits for each of the CN pins. Setting any of the control bits enables the weak pull-downs for the corresponding pins.

When the internal pull-up is selected, the pin uses V_{DD} as the pull-up source voltage. When the internal pull-down is selected, the pins are pulled down to V_{SS} by an internal resistor. Make sure that there is no external pull-up source/pull-down sink when the internal pull-ups/pull-downs are enabled.

Note:	Pull-ups and pull-downs on Change Notification pins should always be disabled whenever the port pin is configured as a digital output.

EXAMPLE 11-1: PORT WRITE/READ EXAMPLE (ASSEMBLY LANGUAGE)

```
MOV     #0xFF00, W0       ; Configure PORTB<15:8> as inputs and PORTB<7:0> as outputs
MOV     W0, TRISB
MOV     #0x00FF, W0       ; Enable PORTB<15:8> digital input buffers
MOV     W0, ANSB
NOP                       ; Delay 1 cycle
BTSS    PORTB, #13        ; Next Instruction
```

EXAMPLE 11-2: PORT WRITE/READ EXAMPLE (C LANGUAGE)

```
TRISB = 0xFF00;           // Configure PORTB<15:8> as inputs and PORTB<7:0> as outputs
ANSB = 0x00FF;            // Enable PORTB<15:8> digital input buffers
NOP();                    // Delay 1 cycle
if(PORTBbits.RB13 == 1)   // execute following code if PORTB pin 13 is set.
{
}
```

NOTES:

REGISTER 17-5: SSPxCON2: MSSPx CONTROL REGISTER 2 (I^2C™ MODE)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
GCEN	ACKSTAT	ACKDT(1)	ACKEN(2)	RCEN(2)	PEN(2)	RSEN(2)	SEN(2)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7 **GCEN:** General Call Enable bit (Slave mode only)
1 = Enables interrupt when a general call address (0000h) is received in the SSPxSR
0 = General call address is disabled

bit 6 **ACKSTAT:** Acknowledge Status bit (Master Transmit mode only)
1 = Acknowledge was not received from slave
0 = Acknowledge was received from slave

bit 5 **ACKDT:** Acknowledge Data bit (Master Receive mode only)(1)
1 = No Acknowledge
0 = Acknowledge

bit 4 **ACKEN:** Acknowledge Sequence Enable bit (Master mode only)(2)
1 = Initiates Acknowledge sequence on SDAx and SCLx pins, and transmits ACKDT data bit; automatically cleared by hardware
0 = Acknowledge sequence is Idle

bit 3 **RCEN:** Receive Enable bit (Master Receive mode only)(2)
1 = Enables Receive mode for I^2C
0 = Receive is Idle

bit 2 **PEN:** Stop Condition Enable bit (Master mode only)(2)
1 = Initiates Stop condition on SDAx and SCLx pins; automatically cleared by hardware
0 = Stop condition is Idle

bit 1 **RSEN:** Repeated Start Condition Enable bit (Master mode only)(2)
1 = Initiates Repeated Start condition on SDAx and SCLx pins; automatically cleared by hardware
0 = Repeated Start condition is Idle

bit 0 **SEN:** Start Condition Enable bit(2)
Master Mode:
1 = Initiates Start condition on SDAx and SCLx pins; automatically cleared by hardware
0 = Start condition is Idle
Slave Mode:
1 = Clock stretching is enabled for both slave transmit and slave receive (stretch is enabled)
0 = Clock stretching is disabled

Note 1: The value that will be transmitted when the user initiates an Acknowledge sequence at the end of a receive.

2: If the I^2C module is active, these bits may not be set (no spooling) and the SSPxBUF may not be written (or writes to the SSPxBUF are disabled).

REGISTER 23-6: FPOR: RESET CONFIGURATION REGISTER

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-0	R/P-1	R/P-1
MCLRE(1)	BORV1(2)	BORV0(2)	I2C1SEL(3)	PWRTEN	—	BOREN1	BOREN0
bit 7							bit 0

Legend:			
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7 **MCLRE:** $\overline{\text{MCLR}}$ Pin Enable bit(1)
1 = $\overline{\text{MCLR}}$ pin is enabled; RA5 input pin is disabled
0 = RA5 input pin is enabled; $\overline{\text{MCLR}}$ is disabled

bit 6-5 **BORV<1:0>:** Brown-out Reset Enable bits(2)
11 = Brown-out Reset is set to the low trip point
10 = Brown-out Reset is set to the middle trip point
01 = Brown-out Reset is set to the high trip point
00 = Downside protection on POR is enabled (Low-Power BOR is selected)

bit 4 **I2C1SEL:** Alternate MSSP1 I^{2}C™ Pin Mapping bit(3)
1 = Default location for SCL1/SDA1 pins (RB8 and RB9)
0 = Alternate location for SCL1/SDA1 pins (ASCL1/RB6 and ASDA1/RB5)

bit 3 **PWRTEN:** Power-up Timer Enable bit
1 = PWRT is enabled
0 = PWRT is disabled

bit 2 **Unimplemented:** Read as ‘0’

bit 1-0 **BOREN<1:0>:** Brown-out Reset Enable bits
11 = BOR is enabled in hardware; SBOREN bit is disabled
10 = BOR is enabled only while device is active and disabled in Sleep; SBOREN bit is disabled
01 = BOR is controlled with the SBOREN bit setting
00 = BOR is disabled in hardware; SBOREN bit is disabled

Note 1: The MCLRE fuse can only be changed when using the VPP-Based ICSP™ mode entry. This prevents a user from accidentally locking out the device from the low-voltage test entry.
2: Refer to Table 26-5 for BOR trip point voltages.
3: Implemented in 28-pin devices only. This bit position must be programmed (= 1) in all other devices for I^{2}C functionality to be available.

TABLE 26-6: DC CHARACTERISTICS: OPERATING CURRENT (IDD)(2)

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**		
IDD Current						
DC20	0.154	0.350	mA	1.8V	+85V°C	0.5 MIPS, FOSC = 1 MHz
	0.301	0.630		3.3V		
	—	.500	mA	1.8V	+125°C	
	—	.800		3.3V		
DC22	0.300	—	mA	1.8V	+85°C	1 MIPS, FOSC = 2 MHz
	0.585	—		3.3V		
DC24	7.76	12.0	mA	3.3V	+85°C	16 MIPS, FOSC = 32 MHz
	—	18.0		3.3V	+125°C	
DC26	1.44	—	mA	1.8V	+85°C	FRC (4 MIPS), FOSC = 8 MHz
	2.71	—		3.3V		
DC30	4.00	28.0	µA	1.8V	+85°C	LPRC (15.5 KIPS), FOSC = 31 kHz
	9.00	55.0		3.3V		
	—	45.0	µA	1.8V	+125°C	
	—	90.0		3.3V		

Note 1: Data in the Typical column is at 3.3V, +25°C, unless otherwise stated.

2: IDD is measured with all peripherals disabled. All I/Os are configured as outputs and set low; PMDx bits are set to '1' and WDT, etc., are all disabled.

TABLE 26-7: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)(2)

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**		
Idle Current (IIDLE)						
DC40	0.035	0.080	mA	1.8V	+85°C	0.5 MIPS, FOSC = 1 MHz
	0.077	0.150		3.3V		
	—	0.160	mA	1.8V	+125°C	
	—	0.300		3.3V		
DC42	0.076	—	mA	1.8V	+85°C	1 MIPS, FOSC = 2 MHz
	0.146	—		3.3V		
DC44	2.52	3.20	mA	3.3V	+85°C	16 MIPS, FOSC = 32 MHz
	—	5.00	mA	3.3V	+125°C	
DC46	0.45	—	mA	1.8V	+85°C	FRC (4 MIPS), FOSC = 8 MHz
	0.76	—	mA	3.3V		
DC50	0.87	18.0	µA	1.8V	+85°C	LPRC (15.5 KIPS), FOSC = 31 kHz
	1.55	40.0	µA	3.3V		
	—	27.0	µA	1.8V	+125°C	
	—	50.0	µA	3.3V		

Note 1: Data in the Typical column is at 3.3V, +25°C, unless otherwise stated.

2: IIDLE is measured with all I/Os configured as outputs and set low; PMDx bits are set to '1' and WDT, etc., are all disabled.

TABLE 26-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

DC CHARACTERISTICS			**Standard Operating Conditions: 1.8V to 3.6V** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical[(1)]**	**Max**	**Units**	**Conditions**		
Power-Down Current (IPD)						
DC60	0.01	0.20	µA	-40°C	1.8V	Sleep Mode[(2)]
	0.03	0.20	µA	+25°C		
	0.06	0.87	µA	+60°C		
	0.20	1.35	µA	+85°C		
	—	8.00	µA	+125ºC		
	0.01	0.54	µA	-40°C	3.3V	
	0.03	0.54	µA	+25°C		
	0.08	1.68	µA	+60°C		
	0.25	2.45	µA	+85°C		
	—	10.00	µA	+125ºC		

Note 1: Data in the Typical column is at 3.3V, +25°C unless otherwise stated.

2: Base IPD is measured with all peripherals and clocks disabled. All I/Os are configured as outputs and set low; PMDx bits are set to ‘1’ and WDT, etc., are all disabled

TABLE 26-23: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ(1)**	**Max.**	**Units**	**Conditions**
SY10	TmcL	MCLR Pulse Width (low)	2	—	—	μs	
SY11	TPWRT	Power-up Timer Period	50	64	90	ms	
SY12	TPOR	Power-on Reset Delay	1	5	10	μs	
SY13	TIOZ	I/O High-Impedance from MCLR Low or Watchdog Timer Reset	—	—	100	ns	
SY20	TWDT	Watchdog Timer Time-out Period	0.85	1.0	1.15	ms	1.32 prescaler
			3.4	4.0	4.6	ms	1:128 prescaler
SY25	TBOR	Brown-out Reset Pulse Width	1	—	—	μs	
SY45	TRST	Internal State Reset Time	—	5	—	μs	
SY55	TLOCK	PLL Start-up Time	—	100	—	μs	
SY65	TOST	Oscillator Start-up Time	—	1024	—	TOSC	
SY71	TPM	Program Memory Wake-up Time	—	1	—	μs	Sleep wake-up with PMSLP = 0

Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

TABLE 26-24: COMPARATOR TIMINGS

Param No.	Symbol	Characteristic	Min	Typ	Max	Units	Comments
300	TRESP	Response Time(1,2)	—	150	400	ns	
301	TMC2OV	Comparator Mode Change to Output Valid(2)	—	—	10	μs	

Note 1: Response time is measured with one comparator input at (VDD – 1.5)/2, while the other input transitions from VSS to VDD.

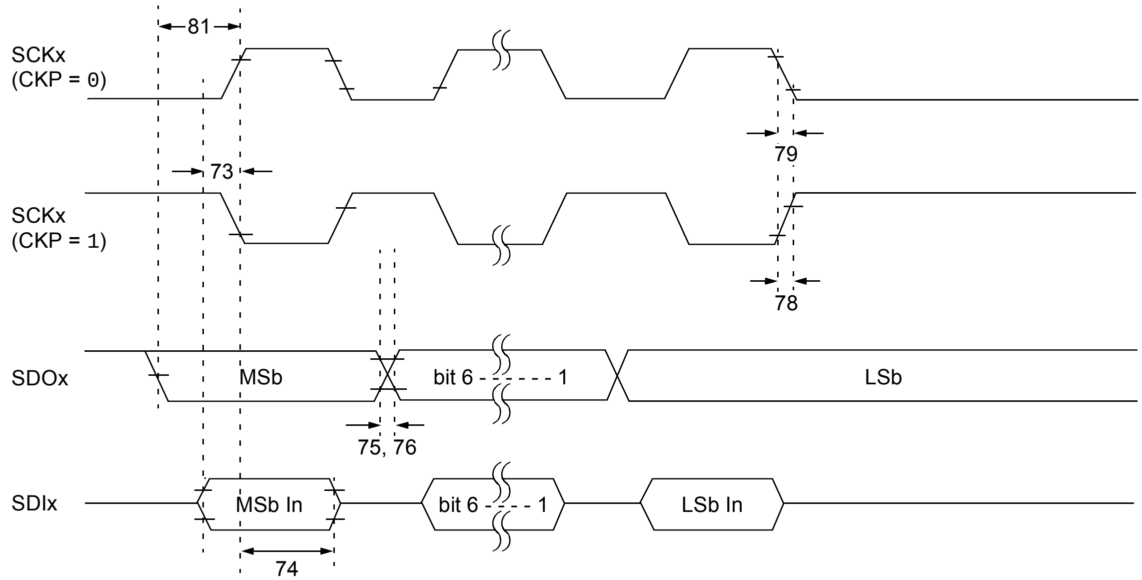
2: Parameters are characterized but not tested.

TABLE 26-25: COMPARATOR VOLTAGE REFERENCE SETTLING TIME SPECIFICATIONS

Param No.	Symbol	Characteristic	Min	Typ	Max	Units	Comments
VR310	TSET	Settling Time(1)	—	—	10	μs	

Note 1: Settling time is measured while CVRSS = 1 and the CVR<3:0> bits transition from '0000' to '1111'.

FIGURE 26-8: EXAMPLE SPI MASTER MODE TIMING (CKE = 1)



Note: Refer to Figure 26-3 for load conditions.

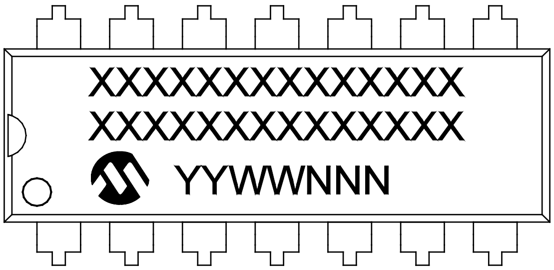
TABLE 26-28: EXAMPLE SPI MODE REQUIREMENTS (MASTER MODE, CKE = 1)

Param. No.	Symbol	Characteristic	Min	Max	Units	Conditions
73	TDIV2SCH, TDIV2SCL	Setup Time of SDIx Data Input to SCKx Edge	35	—	ns	
74	TSCH2DIL, TSCL2DIL	Hold Time of SDIx Data Input to SCKx Edge	40	—	ns	
75	TDOR	SDOx Data Output Rise Time	—	25	ns	
76	TDOF	SDOx Data Output Fall Time	—	25	ns	
78	TSCR	SCKx Output Rise Time (Master mode)	—	25	ns	
79	TSCF	SCKx Output Fall Time (Master mode)	—	25	ns	
81	TDOV2SCH, TDOV2SCL	SDOx Data Output Setup to SCKx Edge	TCY	—	ns	
	FSCK	SCKx Frequency	—	10	MHz	

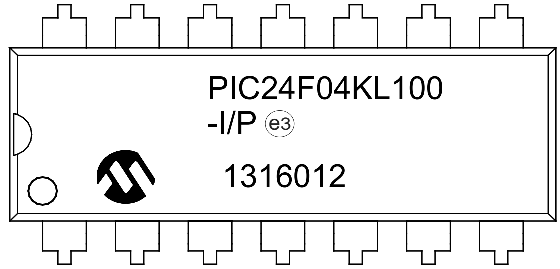
27.0 PACKAGING INFORMATION

27.1 Package Marking Information

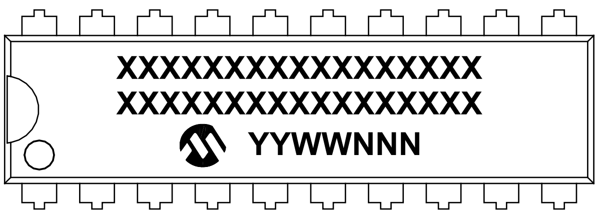
14-Lead PDIP (300 mil)



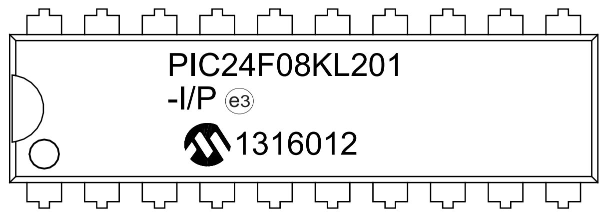
Example



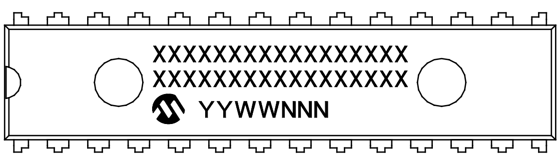
20-Lead PDIP (300 mil)



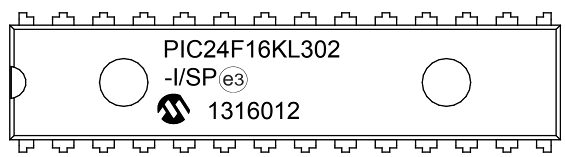
Example



28-Lead SPDIP (.300")



Example

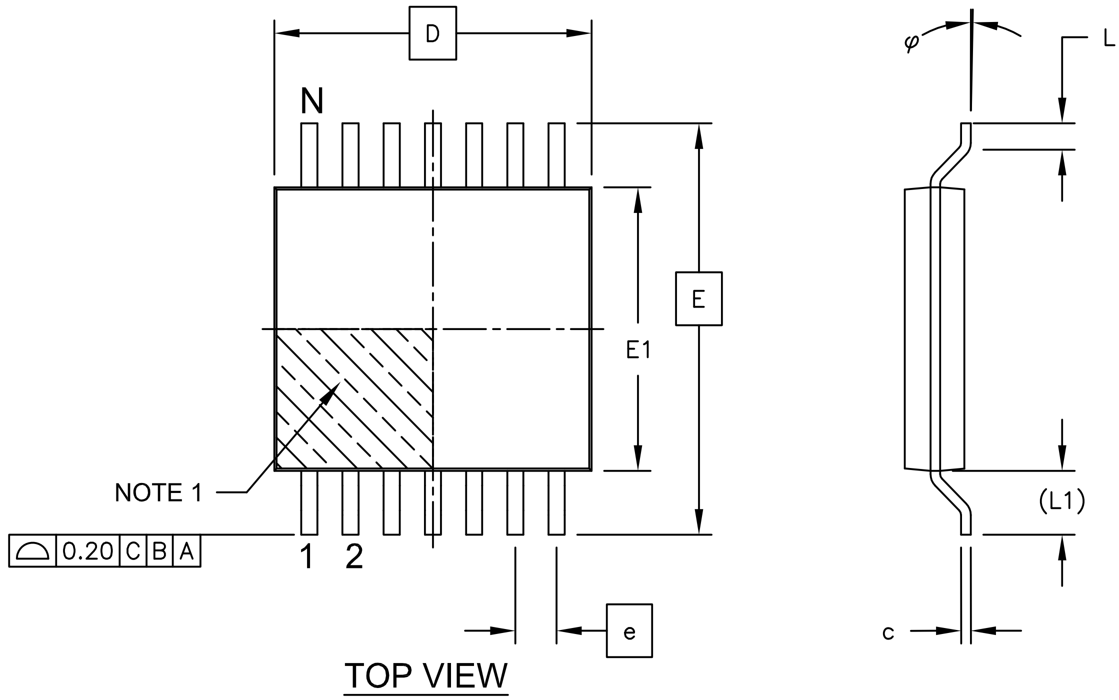


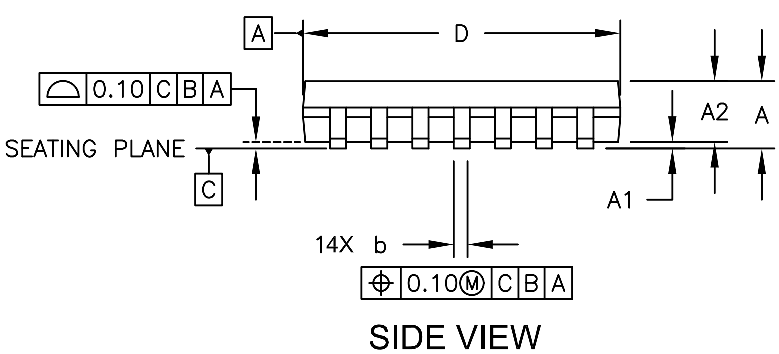
Legend:	XX...X	Product-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

14-Lead Plastic Thin Shrink Small Outline (ST) - 4.4 mm Body [TSSOP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





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